

Type number	Package	Package description	Total product weight
74AHC125BQ	SOT762-1	DHVQFN14	17.66900 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935285542115	13	1	260	30 s	1	240	20 s	3	Bangkok, Thailand; Nijmegen, Netherlands; Suzhou, China	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.05607	80.10000	0.31734
		Polymer	Resin system	Proprietary	0.01393	19.90000
			subTotal		0.07000	100.00000
Die	Doped silicon	Silicon (Si)	7440-21-3	0.21155	100.00000	1.19727
			subTotal	0.21155	100.00000	1.19727
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	6.46226	97.47000	36.57401
		Iron (Fe)	7439-89-6	0.15912	2.40000	0.90056
		Phosphorous (P)	7723-14-0	0.00199	0.03000	0.01126
		Zinc (Zn)	7440-66-6	0.00663	0.10000	0.03752
			subTotal		6.63000	100.00000
Mould Compound	Filler	Silica -amorphous-	7631-86-9	0.73360	7.00000	4.15190
		Silica fused	60676-86-0	8.69840	83.00000	49.22972
	Pigment	Carbon black	1333-86-4	0.05240	0.50000	0.29656
	Polymer	Epoxy resin system	Proprietary	0.62880	6.00000	3.55878
		Phenolic resin	Proprietary	0.36680	3.50000	2.07595
		subTotal		10.48000	100.00000	59.31291
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00660	3.00000	0.03735
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.20306	92.30000	1.14924
		Palladium (Pd)	7440-05-3	0.00682	3.10000	0.03860
		Silver (Ag)	7440-22-4	0.00352	1.60000	0.01992
			subTotal		0.22000	100.00000
Wire	Pure metal	Copper (Cu)	7440-50-8	0.05746	100.00000	0.32520
			subTotal	0.05746	100.00000	0.32520

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